

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Silicon Carbide (SiC)	409-21-2	0.65	100.0	1.11
			Subtotal	0.65	100	1.11
Wire	Impurity	Non hazardous		0	0.01	0
	Pure metal	Copper (Cu)	7440-50-8	0.52	99.99	0.88
			Subtotal	0.52	100	0.88
Die Attach	Hardener	Hardener		0.01	5.0	0.01
	Phenolic resin	Phenolic resin		0.01	5.0	0.01
	Epoxy resin	Epoxy resin system		0.01	5.0	0.01
	Lead alloy	Silver (Ag)	7440-22-4	0.14	85.0	0.24
			Subtotal	0.17	100	0.27
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01	0.03	0.02
	Copper alloy	Zinc (Zn)	7440-66-6	0.06	0.15	0.1
	Copper alloy	Iron (Fe)	7439-89-6	0.88	2.29	1.49
	Copper alloy	Copper (Cu)	7440-50-8	37.12	96.97	63.19
	Copper alloy	Silver (Ag)	7440-22-4	0.21	0.56	0.36
			Subtotal	38.28	100	65.16
Mould Compound	Polymer	Epoxy Phenol Novolac resin (generic)	28064-14-4	2.05	3.5	3.49
	Filler	Silica -amorphous-	7631-86-9	4.69	8.0	7.98
	Filler	Silica fused	60676-86-0	46.86	80.0	79.76
	Carbon Black	Carbon black	1333-86-4	0.29	0.5	0.5
	Polymer	Epoxy resin system		4.69	8.0	7.98
			Subtotal	58.58	100	99.71
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.82	100.0	3.1
			Subtotal	1.82	100	3.1
			Total	100.02	100	170.23

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